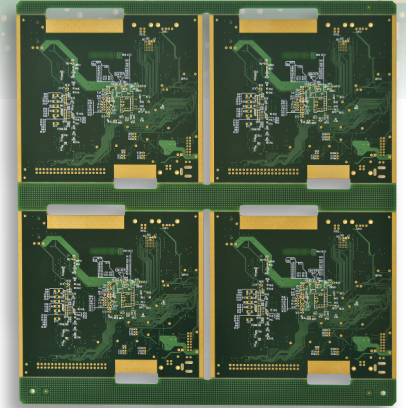


# Multilayer by Icom

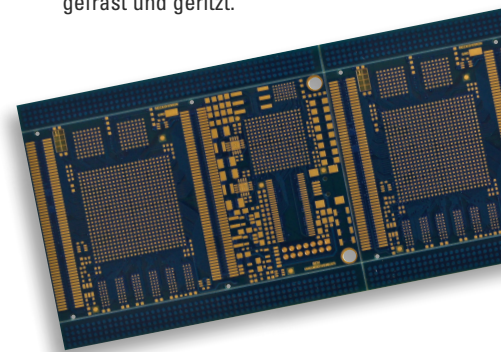
## Features

## Capabilities

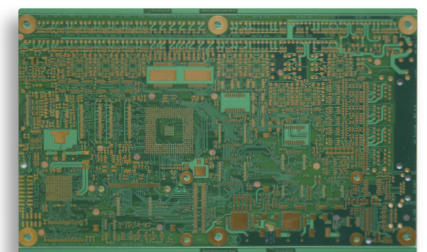
Layers	max. 36 Layers	
Laminate Thickness	FR4, High Tg FR4, Halogen free FR4, G10, BT, P97, PTFE	
Copper thickness	12/18/35/70/105µm	
Approval	UL-approval, Flame class 94V-0, Class 1/2/3	
Specialized laminate	Taconic, Rogers, Neltec, Arlon, further specialized material	
max. Boardsize	max. 610 x 730mm	
Surface finish	Hot air leveling, (Lead or Lead-free) Bondgold for ultrasonic bonding Bondgold for thermalsonic bonding Hardgold for Connectors immersion Tin chem. Au/Ni (immersion gold over nickel) Silver ink or Carbon ink OSP (Entek)	
Soldermask	Liquid, photoimageable Mask, in green or any color Peelable Mask	
Component marking	White or per request	
Outlines	CNC-Routing CNC V-Scoring CNC Milling Laser Milling	
min. Via Diameter	75µm (Laser), 100µm (Mechanical)	
General tolerances	min. Outline tolerances routed	+/-0.075 mm
	min. Holesize diameter	+/-0.050 mm
	min. Hole position tolerance	+/-0.050 mm
	min. Pattern Registration tolerance	+/-0.050 mm
	min. Soldermask Registration tolerance	+/-0.050 mm
General Capabilities	min. Annular ring	0.025 mm
	min. Soldermask bridge	0.050 mm
	plated Gold thickness	0.025µm – 3µm
	immersion gold thickness	0.025µm – 0.6µm
	Twist and Wrap	< 1%
	E/Test Voltage	24V – 300V
	Continuity	5 – 100 Ohms
	Flying Probe test available	
	Capped Vias	



10 Lagen, FR4/1.6mm/70µm Cu, HAL bleifrei, im 4er Nutzen mit beidseitig angefasten Steckern, partiell vergoldet, gefräst und geritzt.



8 Lagen, FR4/1.0mm/18µm Cu, chem. Au/Ni, 0.1mm Vias, blauer Lötstopplack, gefräst und geritzt



6 Lagen, FR4/3.2mm/70µm Cu (Tg150), chem. Au/Ni, Konturen gefräst



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